

# Editorial

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Dear IMAPS member:

I am proud to introduce myself as the new editor of your technical journal. Some, perhaps most of you know me as the General Chair of the IMAPS 2003 Symposium held last November in Boston.

Your society representatives, particularly, Ken Gilleo, IMAP’s VP of Membership and our HQ personnel, have worked diligently to bring this, the first quarterly issue of 2004, to you on time. We consider this Journal to be an important membership benefit and are aware of the necessity to publish it on time every quarter.

This issue addresses the important and critical thermal characteristics that are associated with the design, testing and evaluation of microelectronics packaging.

Hope you enjoy these articles and find them as useful as I did. Perhaps they will serve to expand your technical skills-base at a time when training / re-training has become an uncommon happening.

Please forward directly any feedback that you may wish to convey to me at [dbokil@imaps.org](mailto:dbokil@imaps.org).

Regards,

Delip “Doug” Bokil